

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"20040129576".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:11
L2	38	ECMP and ECMD	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:26
L3	2	"6176952".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:26
L4	35	"6534116"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:27
L5	2	"6534116".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:27
L6	101	205/93.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:34
L7	900	applied adj materials and polishing adj (pad surface) and ("204" "205" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:34
L8	539	applied adj materials\$.as. and polishing adj (pad surface) and ("204" "205" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:34
L9	77	applied adj materials\$.as. and polishing adj (pad surface) and ("204" "205" "451").clas. and (anode cathode electrode)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:44

## EAST Search History

L10	2	"20020130049".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 15:18
L11	11	porous with ceramic same (polishing adj pad) and ("204" "205" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:58
L12	60	poro\$4 with ceramic same (polish\$3) and ("204" "205" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:58
L13	76	poro\$4 with (alumina ceramic) same (polish\$3) and ("204" "205" "451"). clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:58
L14	59	poro\$4 with (alumina ceramic) same (polish\$3) and ("204" "205" "451"). clas. and (semiconductor microelectronic microfeature wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 14:59
L15	17	poro\$4 with (alumina ceramic) same (fir\$3 sinter\$3 coat\$3 seal\$3) same (polish\$3) and ("204" "205" "451"). clas. and (semiconductor microelectronic microfeature wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 15:00
L16	53	electroplat\$3 and poro\$4 with (ceramic alumina!) with resistance	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 15:05
L17	2	"20020020627".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 15:10
L18	10	("20020029961"   "5853559"   "6126798"   "6132587"   "6176992"   "6179982"   "6179983"   "6375823"   "6402925"   "6416647").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/28 15:05
L19	3	"20010024691".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:03

## EAST Search History

L20	140	chen\$-li\$.in. and planarizing and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 15:18
L21	0	("204" "205" "451").clas. and porous near2 alumina! with polish\$3 near (pad surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:03
L22	1	("204" "205" "451").clas. and porous near2 alumina! same polish\$3 near (pad surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:04
L23	4	("204" "205" "451").clas. and porous near2 ceramic same polish\$3 near (pad surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:05
L24	11	("204" "205" "451").clas. and porous near2 ceramic same CMP	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:05
L25	19	porous near2 (ceramic alumina!) same polishing adj (pad surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:11
L26	9	porous near2 (ceramic alumina!) same polishing adj (pad surface) and (wafer semiconductor microelectronic microfeature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:16
L27	101	porous near2 (ceramic alumina!) same (pad surface) and (CMP ECMP) and (wafer semiconductor microelectronic microfeature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:16
L28	62	porous near2 (ceramic alumina!) same (pad surface) and (CMP ECMP) and (wafer semiconductor microelectronic microfeature) and ("204" "205" "451"). clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/28 16:17